# ACM Research Receives 2025 3D InCites Technology Enablement Award

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## Recognized for Innovation in High-Volume Fan-Out Panel-Level Packaging Solutions

FREMONT, Calif., April 10, 2025 (GLOBE NEWSWIRE) -- ACM Research, Inc. ("ACM") (NASDAQ: ACMR), a leading supplier of wafer and panel processing solutions for semiconductor and advanced packaging applications, today announced that its Ultra ECP ap-p tool has won the 2025 *3D InCites* Award in the Technology Enablement category. This award honors companies that have identified and solved critical challenges in the advancement of the heterogeneous integration roadmap, driving the industry forward through cutting-edge solutions and advancements.

ACM's Ultra ECP ap-p system, designed for fan-out panel-level packaging (FOPLP), is the first commercially-available high-volume copper deposition system for the large panel market. By using a horizontal plating approach, it achieves exceptional uniformity and precision across the entire panel. The tool supports 515 mm x 510 mm and 600 mm x 600 mm panel sizes and can be used for plating steps in a variety of processes including pillar, bump and redistribution layer.

"I believe this award recognition from *3D InCites* validates ACM's dedication to innovation in addressing customers' challenges in panel-level packaging (PLP)," said Dr. David Wang, ACM's President and Chief Executive Officer. "As the demand for large chiplets, high-performance graphics processing units and high-density high-bandwidth memory continues to grow, PLP has emerged as a key solution for reducing cost and improving efficiency. The Ultra ECP ap-p system is a vital addition to ACM's expanding FOPLP portfolio, reinforcing our commitment to advancing high-volume manufacturing solutions."

ACM's FOPLP portfolio includes:

- Ultra ECP ap-p for copper deposition
- Ultra C vac-p for flux cleaning
- Ultra C bev-p for bevel etching and cleaning

Announced at the IMAPS Device Packaging Conference, *3D InCites* award winners were selected based on their significant contributions to the advancement of the heterogeneous integration roadmap.

**Forward-Looking Statements**

Certain statements contained in this press release are not historical facts and may be forward-looking statements within the meaning of the Private Securities Litigation Reform Act of 1995. Words such as "plans," "expects," "believes," "anticipates," "designed," and similar words are intended to identify forward-looking statements. Forward-looking statements are based on ACM management's current expectations and beliefs and involve a number of risks and uncertainties that are difficult to predict and that could cause actual results to differ materially from those stated or implied by the forward-looking statements. A description of certain of these risks, uncertainties and other matters can be found in filings ACM makes with the U.S. Securities and Exchange Commission, all of which are available at www.sec.gov. Because forward-looking statements involve risks and uncertainties, actual results and events may differ materially from results and events currently expected by ACM. Readers are cautioned not to place undue reliance on these forward-looking statements, which speak only as of the date hereof. ACM undertakes no obligation to publicly update these forward-looking statements to reflect events or circumstances that occur after the date hereof or to reflect any change in its expectations with regard to these forward-looking statements or the occurrence of unanticipated events.

**About ACM Research, Inc.**

ACM develops, manufactures and sells semiconductor process equipment spanning cleaning, electroplating, stress-free polishing, vertical furnace processes, track, PECVD, and wafer- and panel-level packaging tools, enabling advanced and semi-critical semiconductor device manufacturing. ACM is committed to delivering customized, high-performance, cost-effective process solutions that semiconductor manufacturers can use in numerous manufacturing steps to improve productivity and product yield. For more information, visit www.acmr.com.

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**Media Contact:**
Alyssa Lundeen
Kiterocket
+1 218.398.0776
alundeen@kiterocket.com

**Company Contacts:**
USA
Robert Metter
+1 503.367.9753

China
Xi Wang
ACM Research (Shanghai), Inc.
+86 21 50808868

Korea
ACM Research (Korea), Inc.
+82-70-41006699.

Taiwan
David Chang
+886 921999884

Singapore
Adrian Ong
+65 8813-1107